

# Specification of Thermoelectric Module

## TEHC1-12710

### Description

The 127 couples, 40 mm × 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74 °C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### Features

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

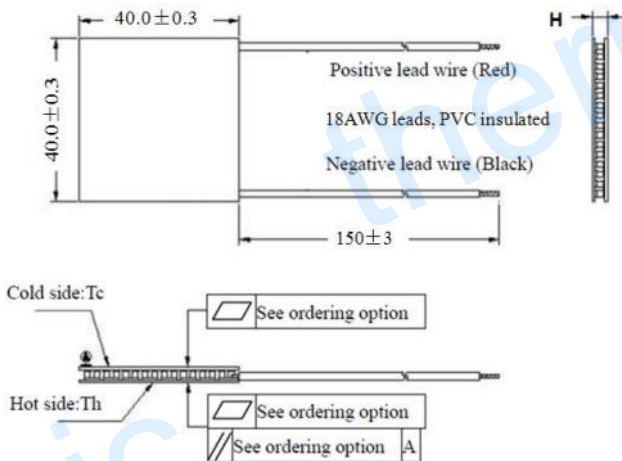
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	16.8	18.08	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	10.1	10.1	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	108.0	117.8	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	1.25	1.38	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.6±0.1	0:0.08/0.08	150±3/Specify
TF	1:3.6±0.03	1:0.03/0.03	150±3/Specify

Eg. TF01: Thickness 3.6±0.1(mm) and Flatness 0.03/0.03(mm)

### Manufacturing Options

#### A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

#### C. Ceramics:

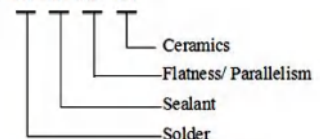
1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

### Naming for the Module

TEHC1-12710- X -X - X - X



TEHC1-12710-T100-NS-TF01 -A1O

T100: BiSn(Tmelt=138°C)

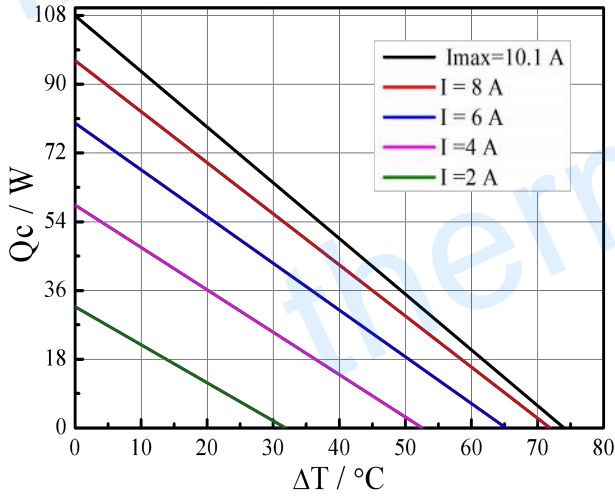
NS: No sealing

A1O: Alumina white 96%

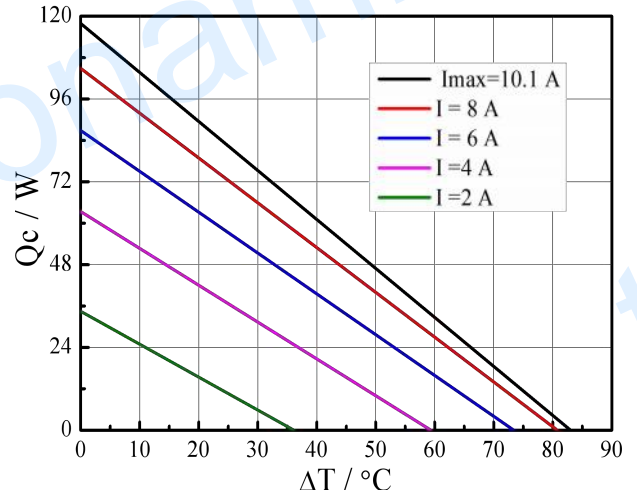
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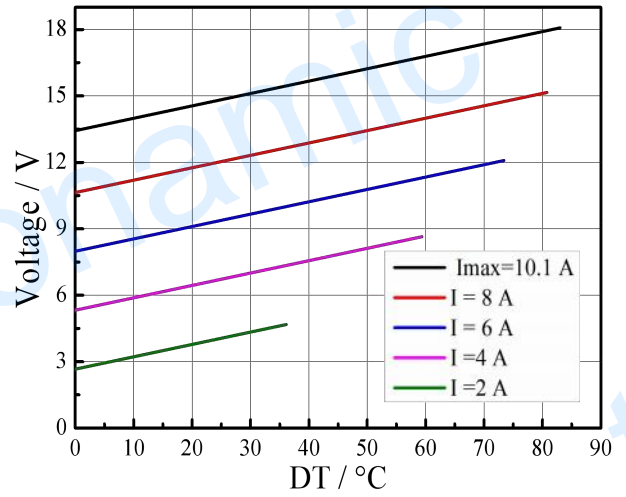
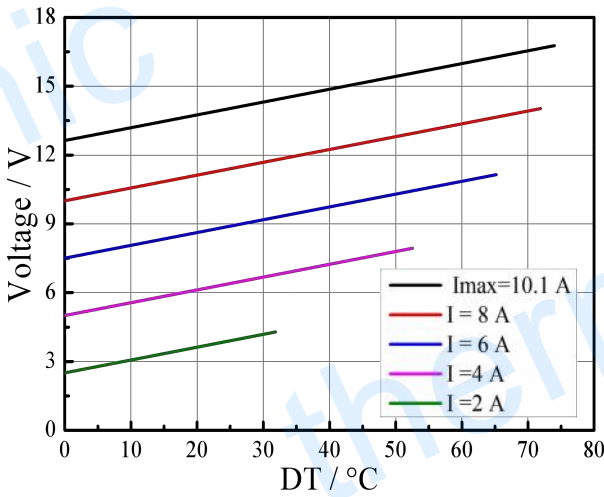
Performance Curves at  $T_h=27\text{ }^\circ\text{C}$



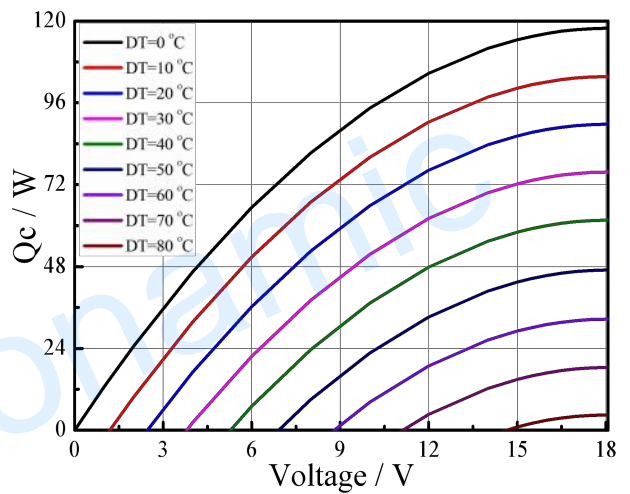
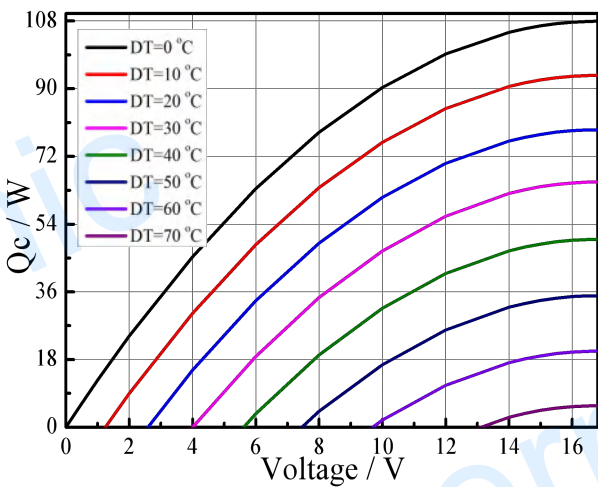
Performance Curves at  $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph  $Q_c = f(\Delta T)$



Standard Performance Graph  $V = f(\Delta T)$

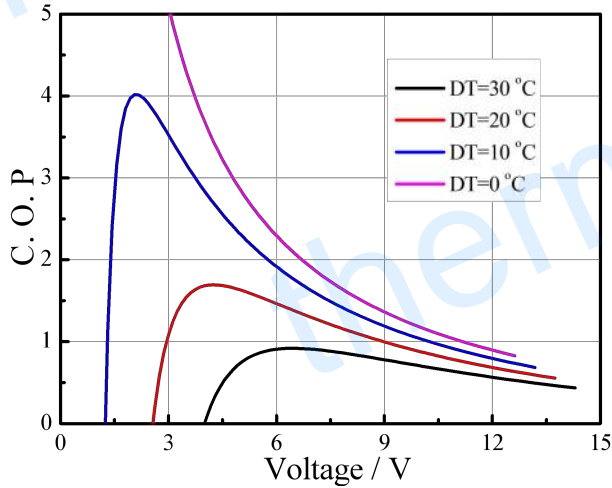


Standard Performance Graph  $Q_c = f(V)$

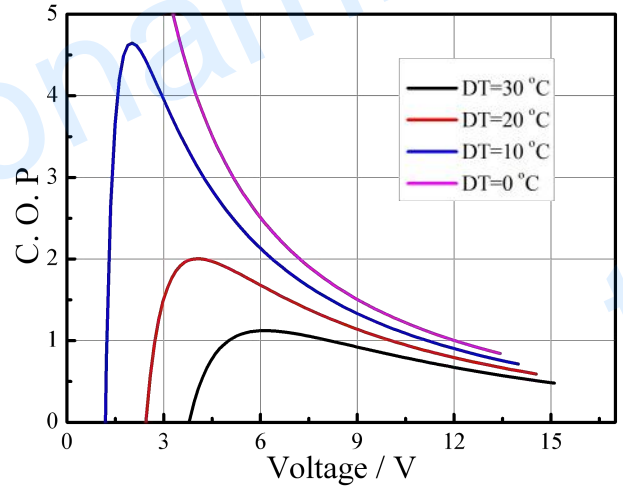
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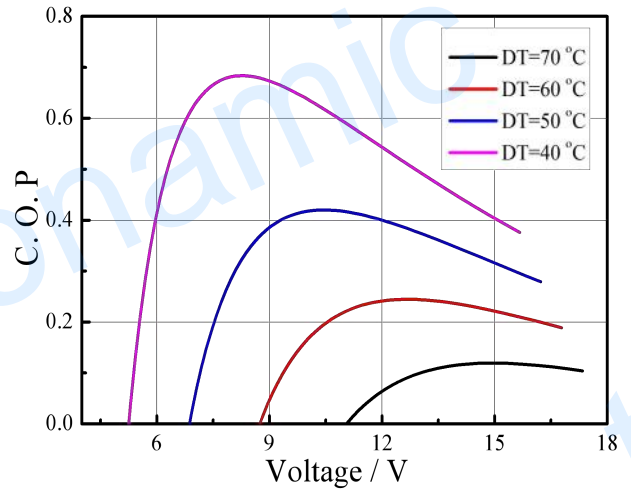
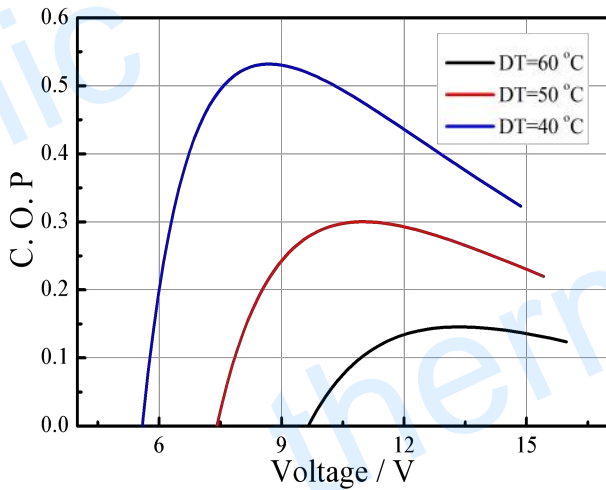
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

## Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below  $I_{max}$  or  $V_{max}$
- Operation or storage module below 100 °C
- Work under DC